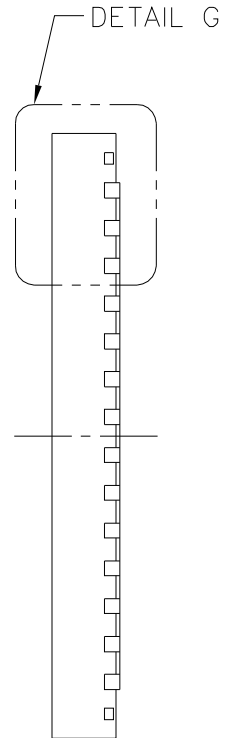
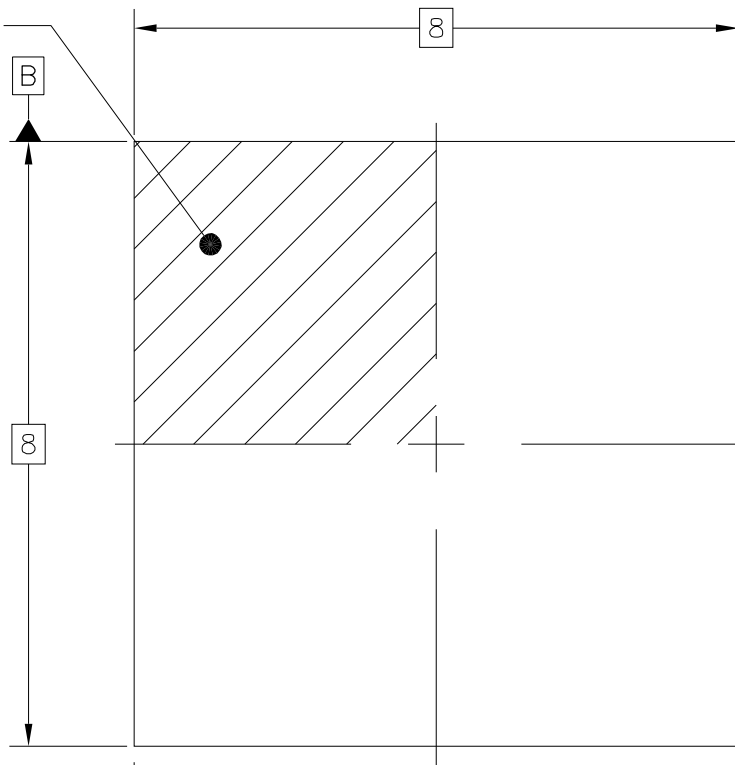


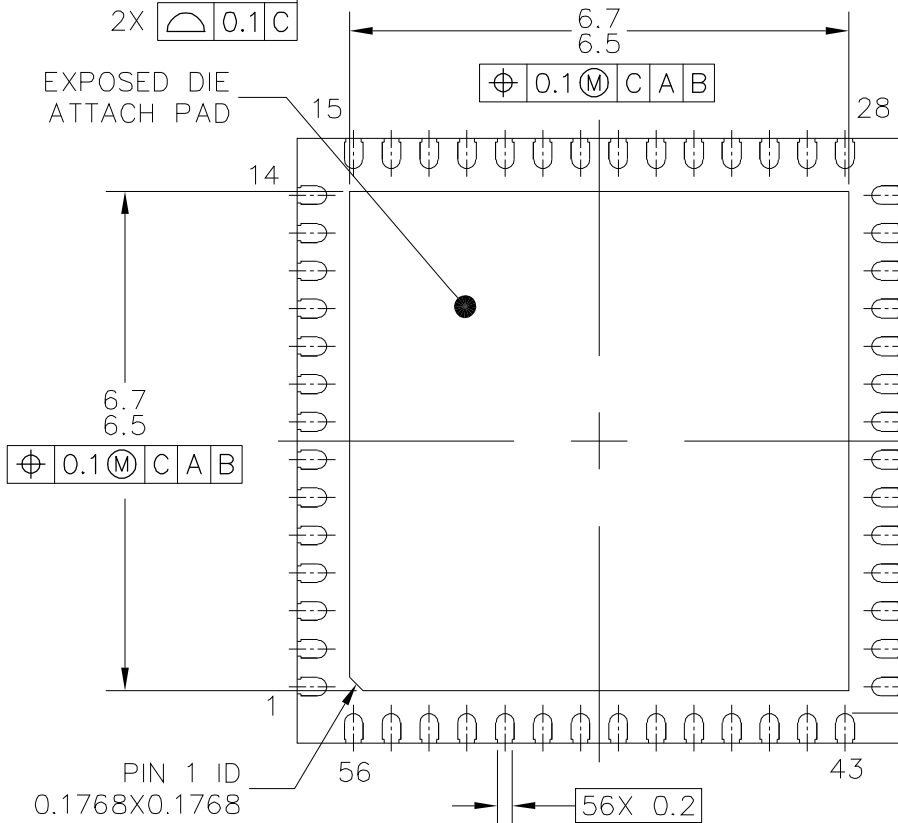


PIN 1
INDEX AREA



2X $\frac{\text{D}}{2}$ 0.1 C

EXPOSED DIE ATTACH PAD



56X 0.30
0.18
 $\frac{\text{D}}{2}$ 0.1 M A B C
0.05 M C

52X 0.5

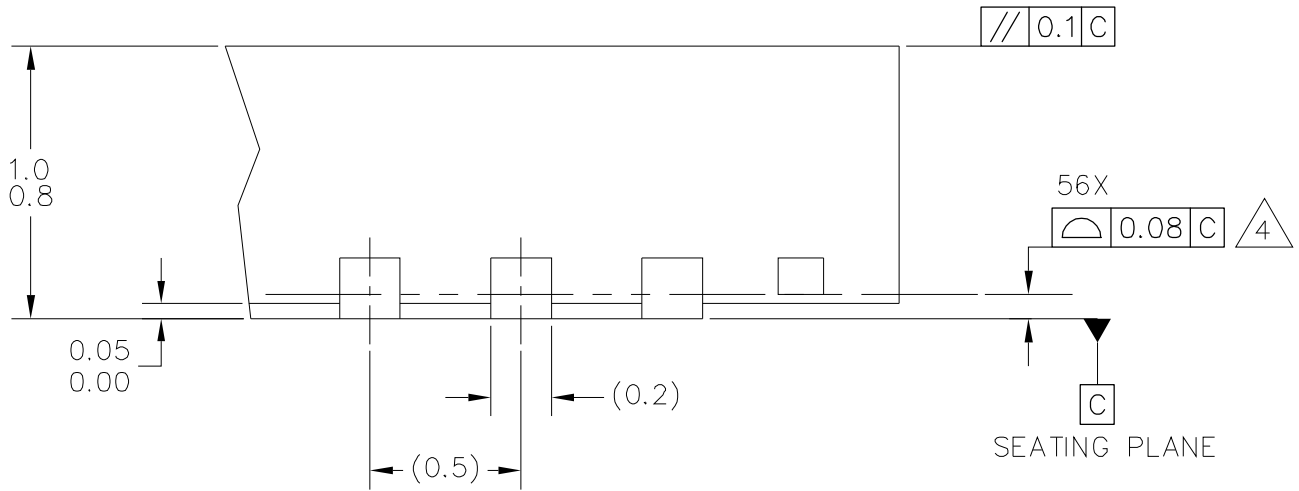
0.25

56X 0.5
0.3

56X 0.2

PIN 1 ID
0.1768X0.1768

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TITLE: QFN, THERMALLY ENHANCED, 8 X 8 X 0.9, 0.5 PITCH, 56 TERMINAL	DOCUMENT NO: 98ASA00654D	REV: A
	STANDARD: NON-JEDEC	
	SOT684-17	13 JAN 2016




DETAIL G
VIEW ROTATED 90°CW

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	STANDARD: NON-JEDEC		
	SOT684-17		13 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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		STANDARD: NON-JEDEC	
		SOT684-17	13 JAN 2016